

K4Q153211M, K4Q153212M**CMOS DRAM****512K x 32Bit CMOS Quad $\overline{\text{CAS}}$ DRAM with EDO****DESCRIPTION**

This is a 524,288 x 32 bit Extended Data Out CMOS DRAM. Extended Data Out Mode offers high speed random access of memory cells within the same row, so called Hyper Page Mode. Power supply voltage (+5.0V or +3.3V), refresh cycle 1K, access time (-50 or -60), power consumption(Normal or Low power) and SOJ package type are optional features of this family. All of this family have $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ -only refresh and Hidden refresh capabilities. Furthermore, Self-refresh operation is available in L-version. This 512Kx32 EDO Mode Quad $\overline{\text{CAS}}$ DRAM is fabricated using Samsung's advanced CMOS process to realize high band-width, low power consumption and high reliability.

FEATURES**• Part Identification**

- K4Q153211M-JC (5.0V, 1K Ref.)
- K4Q153211M-JL (5.0V, 1K Ref. LP)
- K4Q153212M-JC (3.3V, 1K Ref.)
- K4Q153212M-JL (3.3V, 1K Ref. LP)

• Active Power Dissipation

Unit : mW

Speed	3.3V	5.0V
-50	-	880
-60	540	825

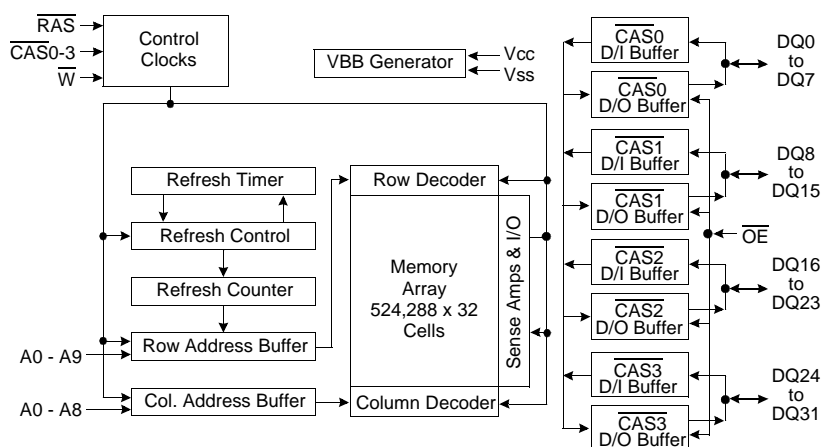
• Refresh Cycles

Part NO.	V _{CC}	Refresh cycle	Refresh period	
			Normal	L-ver
153211M-J	5.0V	1K	16ms	128ms
153212M-J	3.3V	1K	16ms	128ms

• Performance Range

Speed	t _{RAC}	t _{CAC}	t _{RC}	t _{HPC}	Remark
-50	50ns	15ns	84ns	20ns	5.0V only
-60	60ns	17ns	104ns	27ns	5V/3.3V

- Extended Data Out Mode operation (Fast Page Mode with Extended Data Out)
- Four separate $\overline{\text{CAS}}$ pins provide for separate I/O operation
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh capability
- $\overline{\text{RAS}}$ -only and Hidden refresh capability
- Self-refresh capability (L-ver only)
- TTL(5V)/LVTTTL(3.3V) compatible inputs and outputs
- Early Write or output enable controlled write
- JEDEC Standard pinout
- Plastic SOJ 400mil x 1125mil package
- Single +5.0V±0.5V power supply(5V product)
- Single +3.3V±0.3V power supply(3.3V product)

FUNCTIONAL BLOCK DIAGRAM

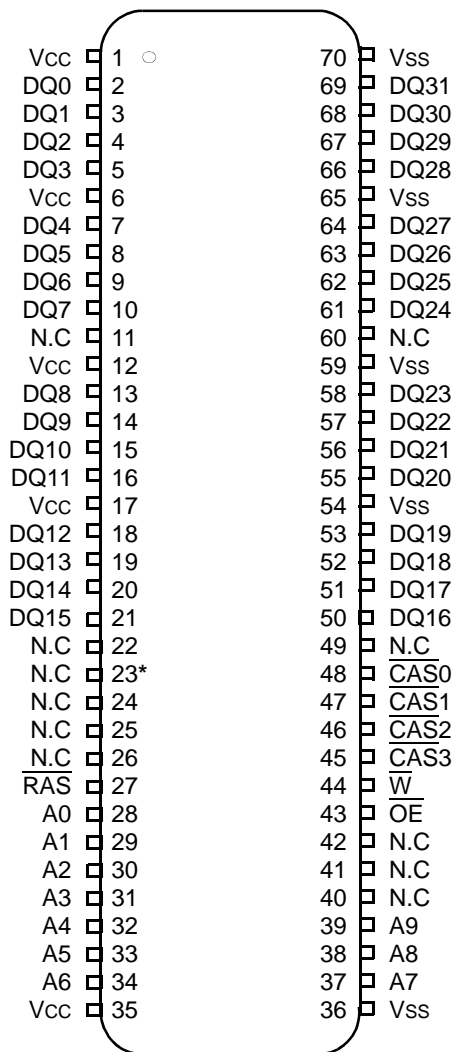
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K4Q153211M, K4Q153212M

CMOS DRAM

PIN CONFIGURATION (Top Views)



Pin Name	Pin Function
A0 - A9	Address Inputs
DQ0 - 31	Data In/Out
RAS	Row Address Strobe
CAS0 - 3	Column Address Strobe
W	Read/Write Input
OE	Data Output Enable
Vss	Ground
Vcc	Power(+5V)
	Power(+3.3V)
N.C	No Connection

* Pin23 : must be NC or Vss

K4Q153211(2)M-J

J : 400mil 70pin SOJ

K4Q153211M, K4Q153212M**CMOS DRAM****ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Rating		Units
		3.3V	5V	
Voltage on any pin relative to Vss	V _{IN} , V _{OUT}	-0.5 to +4.6	-1.0 to +7.0	V
Voltage on Vcc supply relative to Vss	V _{CC}	-0.5 to +4.6	-1.0 to +7.0	V
Storage Temperature	T _{stg}	-55 to +150	-55 to +150	°C
Power Dissipation	P _D	1	1	W
Short Circuit Output Current	I _{os} Address	50	50	mA

* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltage referenced to Vss, T_A= 0 to 70°C)

Parameter	Symbol	3.3V			5V			Units
		Min	Typ	Max	Min	Typ	Max	
Supply Voltage	V _{CC}	3.0	3.3	3.6	4.5	5.0	5.5	V
Ground	V _{SS}	0	0	0	0	0	0	V
Input High Voltage	V _{IH}	2.2	-	V _{CC} +0.3 ^{*1}	2.4	-	V _{CC} +1.0 ^{*1}	V
Input Low Voltage	V _{IL}	-0.3 ^{*2}	-	0.8	-1.0 ^{*2}	-	0.8	V

*1 : V_{CC}+1.3V/15ns(3.3V), V_{CC}+2.0V/15ns(5V), Pulse width is measured at V_{CC}

*2 : -1.3V/15ns(3.3V), -2.0V/20ns(5V), Pulse width is measured at V_{SS}

DC AND OPERATING CHARACTERISTICS (Recommended operating conditions unless otherwise noted.)

Max	Parameter	Symbol	Min	Max	Units
3.3V	Input Leakage Current (Any input 0≤V _{IN} ≤V _{IN} +0.3V, all other input pins not under test=0 Volt)	I _{I(L)}	-5	5	μA
	Output Leakage Current (Data out is disabled, 0V≤V _{OUT} ≤V _{CC})	I _{O(L)}	-5	5	μA
	Output High Voltage Level(I _{OH} =-2mA)	V _{OH}	2.4	-	V
	Output Low Voltage Level(I _{OL} =2mA)	V _{OL}	-	0.4	V
5V	Input Leakage Current (Any input 0≤V _{IN} ≤V _{IN} +0.5V, all other input pins not under test=0 Volt)	I _{I(L)}	-5	5	μA
	Output Leakage Current (Data out is disabled, 0V≤V _{OUT} ≤V _{CC})	I _{O(L)}	-5	5	μA
	Output High Voltage Level(I _{OH} =-5mA)	V _{OH}	2.4	-	V
	Output Low Voltage Level(I _{OL} =4.2mA)	V _{OL}	-	0.4	V

K4Q153211M, K4Q153212M**CMOS DRAM****DC AND OPERATING CHARACTERISTICS** (Continued)

Symbol	Power	Speed	Max		Units
			K4Q153212M-J	K4Q153211M-J	
I _{CC1}	Don't care	-50	-	160	mA
		-60	150	150	mA
I _{CC2}	Normal L-ver	Don't care	-	2	mA
			1	1	mA
I _{CC3}	Don't care	-50	-	160	mA
		-60	150	150	mA
I _{CC4}	Don't care	-50	-	110	mA
		-60	100	100	mA
I _{CC5}	Normal L-ver	Don't care	500	1000	uA
			300	500	uA
I _{CC6}	Don't care	-50	-	160	mA
		-60	150	150	mA
I _{CC7}	L-ver	Don't care	300	500	uA
I _{CCS}	L-ver	Don't care	200	300	uA

I_{CC1}* : Operating Current (\overline{RAS} and \overline{CAS} cycling @trc=min.)

I_{CC2} : Standby Current ($\overline{RAS} = \overline{CAS} = \overline{W} = V_{IH}$)

I_{CC3}* : \overline{RAS} -only Refresh Current ($\overline{CAS} = V_{IH}$, \overline{RAS} , Address cycling @trc=min.)

I_{CC4}* : Hyper Page Mode Current ($\overline{RAS} = V_{IL}$, \overline{CAS} , Address cycling @tHPC=min.)

I_{CC5} : Standby Current ($\overline{RAS} = \overline{CAS} = \overline{W} = V_{CC}-0.2V$)

I_{CC6}* : \overline{CAS} -Before- \overline{RAS} Refresh Current (\overline{RAS} , \overline{CAS} cycling @trc=min.)

I_{CC7} : Battery back-up current, Average power supply current, Battery back-up mode

Input high voltage(V_{IH}) = $V_{CC}-0.2V$, Input low voltage(V_{IL}) = 0.2V, $\overline{CAS} = 0.2V$,

Din = Don't care, trc = 125us(1K/L-ver)

t_{RAS} = t_{RASmin}~300ns

I_{CCS} : Self Refresh Current

$\overline{RAS}=\overline{CAS}0\sim3 = V_{IL}$, $\overline{W} = \overline{OE} = A0 \sim A9 = V_{CC}-0.2V$ or 0.2V,

DQ0 ~ DQ31 = $V_{CC}-0.2V$, 0.2V or Open

***Note :** I_{CC1}, I_{CC3}, I_{CC4} and I_{CC6} are dependent on output loading and cycle rates. Specified values are obtained with the output open. I_{CC} is specified as an average current. In I_{CC1}, I_{CC3} and I_{CC6}, address can be changed maximum once while $\overline{RAS}=V_{IL}$. In I_{CC4}, address can be changed maximum once within one Hyper page mode cycle time, t_{HPC}.

K4Q153211M, K4Q153212M**CMOS DRAM****CAPACITANCE** ($T_A=25^\circ\text{C}$, $V_{CC}=5\text{V}$ or 3.3V , $f=1\text{MHz}$)

Parameter	Symbol	Min	Max	Units
Input capacitance [A0 ~ A9]	CIN1	-	5	pF
Input capacitance [$\overline{\text{RAS}}$, $\overline{\text{CASx}}$, $\overline{\text{W}}$, $\overline{\text{OE}}$]	CIN2	-	7	pF
Output capacitance [DQ0 - DQ31]	CDQ	-	7	pF

AC CHARACTERISTICS ($0^\circ\text{C}\leq T_A\leq 70^\circ\text{C}$, See note 1,2)Test condition (5V device) : $V_{CC}=5.0\text{V}\pm 0.5\text{V}$, $V_{ih}/V_{il}=2.4/0.8\text{V}$, $V_{oh}/V_{ol}=2.0/0.8\text{V}$ Test condition (3.3V device) : $V_{CC}=3.3\text{V}\pm 0.3\text{V}$, $V_{ih}/V_{il}=2.2/0.8\text{V}$, $V_{oh}/V_{ol}=2.0/0.8\text{V}$

Parameter	Symbol	-50*1		-60		Units	Notes
		Min	Max	Min	Max		
Random read or write cycle time	t _{RC}	84		104		ns	
Read-modify-write cycle time	t _{RWC}	115		140		ns	
Access time from $\overline{\text{RAS}}$	t _{RAC}		50		60	ns	3,4,10
Access time from $\overline{\text{CAS}}$	t _{CAC}		15		17	ns	3,4,5,18
Access time from column address	t _{AA}		25		30	ns	3,10
$\overline{\text{CAS}}$ to output in Low-Z	t _{CLZ}	3		3		ns	3,18
Output buffer turn-off delay from $\overline{\text{CAS}}$	t _{CEZ}	3	13	3	15	ns	6,11,18
$\overline{\text{OE}}$ to output in Low-Z	t _{OLZ}	3		3		ns	3
Transition time (rise and fall)	t _T	2	50	2	50	ns	2
$\overline{\text{RAS}}$ precharge time	t _{RP}	30		40		ns	
$\overline{\text{RAS}}$ pulse width	t _{RAS}	50	10K	60	10K	ns	
$\overline{\text{RAS}}$ hold time	t _{RSH}	13		17		ns	14
$\overline{\text{CAS}}$ hold time	t _{CSH}	40		48		ns	17
$\overline{\text{CAS}}$ pulse width	t _{CAS}	8	10K	12	10K	ns	23
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	t _{RCD}	20	35	20	43	ns	4,16
$\overline{\text{RAS}}$ to column address delay time	t _{RAD}	15	25	15	30	ns	10
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	t _{CRP}	5		5		ns	15
Row address set-up time	t _{ASR}	0		0		ns	
Row address hold time	t _{RAH}	10		10		ns	
Column address set-up time	t _{ASC}	0		0		ns	16
Column address hold time	t _{CAH}	8		10		ns	16
Column address to $\overline{\text{RAS}}$ lead time	t _{RAL}	25		30		ns	
Read command set-up time	t _{RCS}	0		0		ns	
Read command hold time referenced to $\overline{\text{CAS}}$	t _{RCH}	0		0		ns	8,15
Read command hold time referenced to $\overline{\text{RAS}}$	t _{RRH}	0		0		ns	8
Write command hold time	t _{WCH}	10		10		ns	14
Write command pulse width	t _{WP}	10		10		ns	
Write command to $\overline{\text{RAS}}$ lead time	t _{RWL}	13		15		ns	
Write command to $\overline{\text{CAS}}$ lead time	t _{CWL}	8		10		ns	17

Note) *1 : 5V only



K4Q153211M, K4Q153212M**CMOS DRAM****AC CHARACTERISTICS** (Continued)

Parameter	Symbol	-50 ^{*1}		-60		Units	Notes
		Min	Max	Min	Max		
Data set-up time	tDS	0		0		ns	9
Data hold time	tDH	8		10		ns	9
Refresh period (1K, Normal)	tREF		16		16	ms	
Refresh period (L-ver)	tREF		128		128	ms	
Write command set-up time	twCS	0		0		ns	7,16
$\overline{\text{CAS}}$ to $\overline{\text{W}}$ delay time	tCWD	32		36		ns	7,14
$\overline{\text{RAS}}$ to $\overline{\text{W}}$ delay time	trWD	67		79		ns	7
Column address $\overline{\text{W}}$ delay time	tAWD	42		49		ns	7
$\overline{\text{CAS}}$ precharge to $\overline{\text{W}}$ delay time	tCPWD	47		54		ns	7
$\overline{\text{CAS}}$ set-up time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh)	tCSR	5		5		ns	16
$\overline{\text{CAS}}$ hold time ($\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh)	tCHR	10		10		ns	15
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ precharge time	trPC	5		5		ns	16
Access time from $\overline{\text{CAS}}$ precharge	tCPA		28		35	ns	3,15
Hyper Page mode cycle time	tHPC	20		27		ns	12,19
Hyper Page read-modify-write cycle time	tHPRWC	47		56		ns	12,19
$\overline{\text{CAS}}$ precharge time (Hyper Page cycle)	tCP	7		7		ns	20
$\overline{\text{RAS}}$ pulse width (Hyper Page cycle)	trASP	50	200K	60	200K	ns	
$\overline{\text{RAS}}$ hold time from $\overline{\text{CAS}}$ precharge	trHCP	30		35		ns	
$\overline{\text{OE}}$ access time	toEA		13		15	ns	21
$\overline{\text{OE}}$ to data delay	toED	13		15		ns	22
Output buffer turn off delay time from $\overline{\text{OE}}$	toEZ	3	13	3	15	ns	6
$\overline{\text{OE}}$ command hold time	toEH	13		15		ns	
Output data hold time	tDOH	5		5		ns	
Output buffer turn off delay from $\overline{\text{RAS}}$	trEZ	3	13	3	15	ns	6,11
Output buffer turn off delay from $\overline{\text{W}}$	twEZ	3	13	3	15	ns	6
$\overline{\text{W}}$ to data delay	twED	15		15		ns	
$\overline{\text{OE}}$ to $\overline{\text{CAS}}$ hold time	toCH	5		5		ns	
$\overline{\text{CAS}}$ hold time to $\overline{\text{OE}}$	tCHO	5		5		ns	
$\overline{\text{OE}}$ precharge time	toEP	5		5		ns	
$\overline{\text{W}}$ pulse width (Hyper Page Cycle)	twPE	5		5		ns	
$\overline{\text{RAS}}$ pulse width ($\overline{\text{C}}$ -B- $\overline{\text{R}}$ self refresh)	trASS	100		100		us	25,26,27
$\overline{\text{RAS}}$ precharge time ($\overline{\text{C}}$ -B- $\overline{\text{R}}$ self refresh)	trPS	90		110		ns	25,26,27
$\overline{\text{CAS}}$ hold time ($\overline{\text{C}}$ -B- $\overline{\text{R}}$ self refresh)	tCHS	-50		-50		ns	25,26,27
Hold time $\overline{\text{CAS}}$ low to $\overline{\text{CAS}}$ high	tCLCH	5		5		ns	13,24

Note) ^{*1} : 5V only

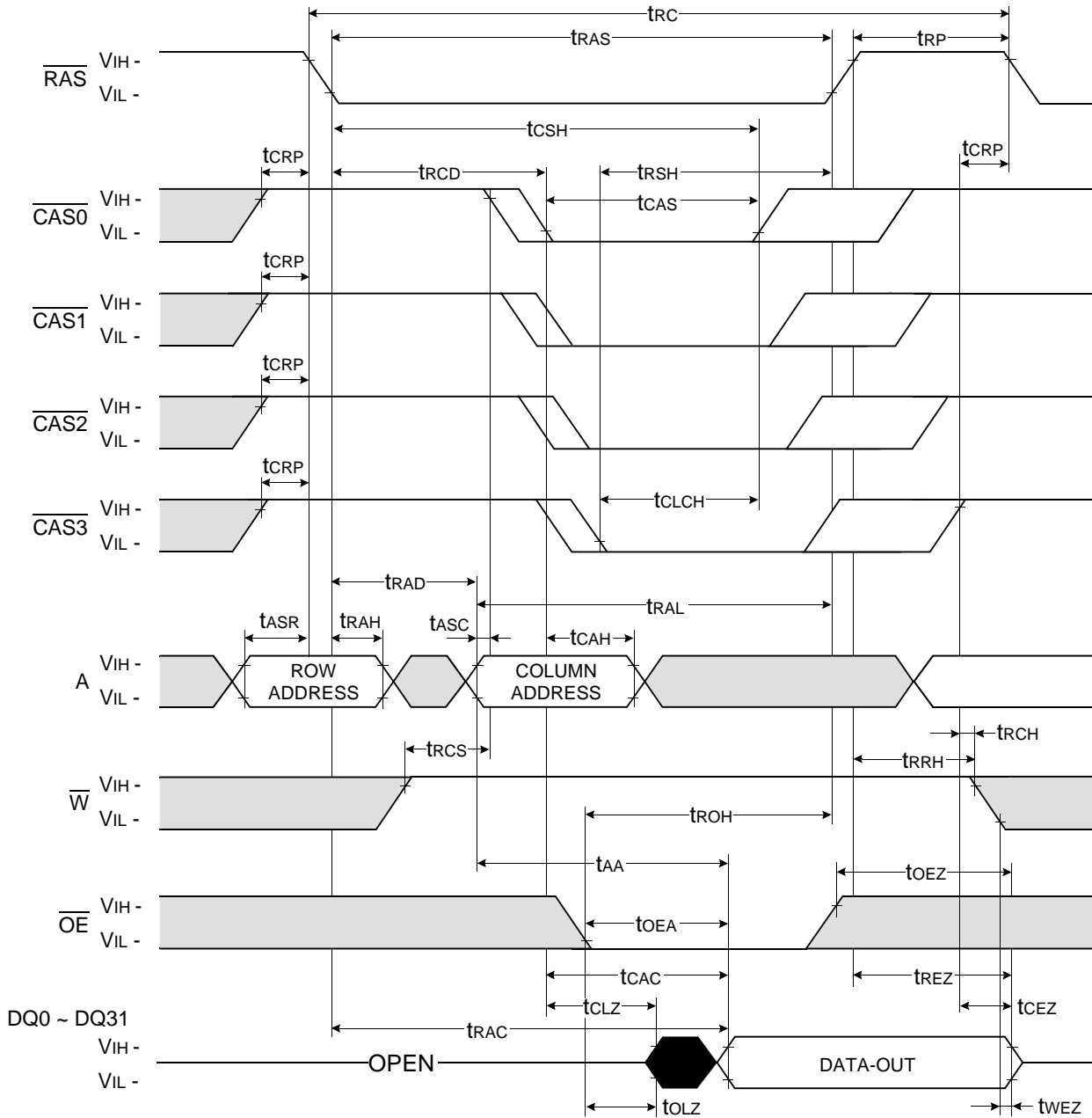
K4Q153211M, K4Q153212M**CMOS DRAM****NOTES**

1. An initial pause of 200us is required after power-up followed by any 8 $\overline{\text{RAS}}$ -only refresh or $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles before proper device operation is achieved.
2. $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ are reference levels for measuring timing of input signals.
Transition times are measured between $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ and are assumed to be 2ns for all inputs.
3. Measured with a load equivalent to 1 TTL load and 50pF.
4. Operation within the $t_{\text{RCD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met. $t_{\text{RCD}}(\text{max})$ is specified as a reference point only.
If t_{RCD} is greater than the specified $t_{\text{RCD}}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
5. Assumes that $t_{\text{RCD}} \geq t_{\text{RCD}}(\text{max})$.
6. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL} .
7. t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPWD} are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{\text{WCS}} \geq t_{\text{WCS}}(\text{min})$, the cycle is an early write cycle and the data output will remain high impedance for the duration of the cycle. If $t_{\text{CWD}} \geq t_{\text{CWD}}(\text{min})$, $t_{\text{RWD}} \geq t_{\text{RWD}}(\text{min})$, $t_{\text{AWD}} \geq t_{\text{AWD}}(\text{min})$ and $t_{\text{CPWD}} \geq t_{\text{CPWD}}(\text{min})$, then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
9. These parameters are referenced to the first $\overline{\text{CAS}}$ falling edge in early write cycles and to \overline{W} falling edge in $\overline{\text{OE}}$ controlled write cycle and read-modify-write cycles.
10. Operation within the $t_{\text{RAD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met. $t_{\text{RAD}}(\text{max})$ is specified as a reference point only.
If t_{RAD} is greater than the specified $t_{\text{RAD}}(\text{max})$ limit, then access time is controlled by t_{AA} .
11. If $\overline{\text{RAS}}$ goes high before $\overline{\text{CAS}}$ high going, the open circuit condition of the output is achieved by $\overline{\text{CAS}}$ high going.
If $\overline{\text{CAS}}$ goes high before $\overline{\text{RAS}}$ high going, the open circuit condition of the output is achieved by $\overline{\text{RAS}}$ high going.
12. $t_{\text{ASC}} \geq 6\text{ns}$, Assume $t_{\text{T}} = 2.0\text{ns}$.
13. In order to hold the address latched by the first $\overline{\text{CAS}}$ going low, the parameter t_{CLCH} must be met.
14. The last $\overline{\text{CASx}}$ edge to go low.
15. The last $\overline{\text{CASx}}$ edge to go high.
16. The first $\overline{\text{CASx}}$ edge to go low.
17. The first $\overline{\text{CASx}}$ edge to go high.
18. Output parameter is referenced to corresponding $\overline{\text{CASx}}$ input.
19. The last rising $\overline{\text{CASx}}$ edge to next cycle's last rising $\overline{\text{CASx}}$ edge.
20. The last rising $\overline{\text{CASx}}$ edge to first falling $\overline{\text{CASx}}$ edge.
21. The first DQx controlled by the first $\overline{\text{CASx}}$ to go low.
22. The last DQx controlled by the last $\overline{\text{CASx}}$ to go high.
23. Each $\overline{\text{CASx}}$ must meet minimum pulse width.
24. The last falling $\overline{\text{CASx}}$ edge to the first rising $\overline{\text{CASx}}$ edge.
25. If $t_{\text{RASS}} \geq 100\text{us}$, then $\overline{\text{RAS}}$ precharge time must use t_{RPS} instead of t_{RP} .
26. For $\overline{\text{RAS}}$ -only refresh and burst $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh mode, 1024(1K) cycles of burst refresh must be executed within 16ms before and after self refresh, in order to meet refresh specification.
27. For distributed $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ with 15.6us interval, $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh should be executed with in 15.6us immediately before and after self refresh in order to meet refresh specification.

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2 WORDS READ CYCLE



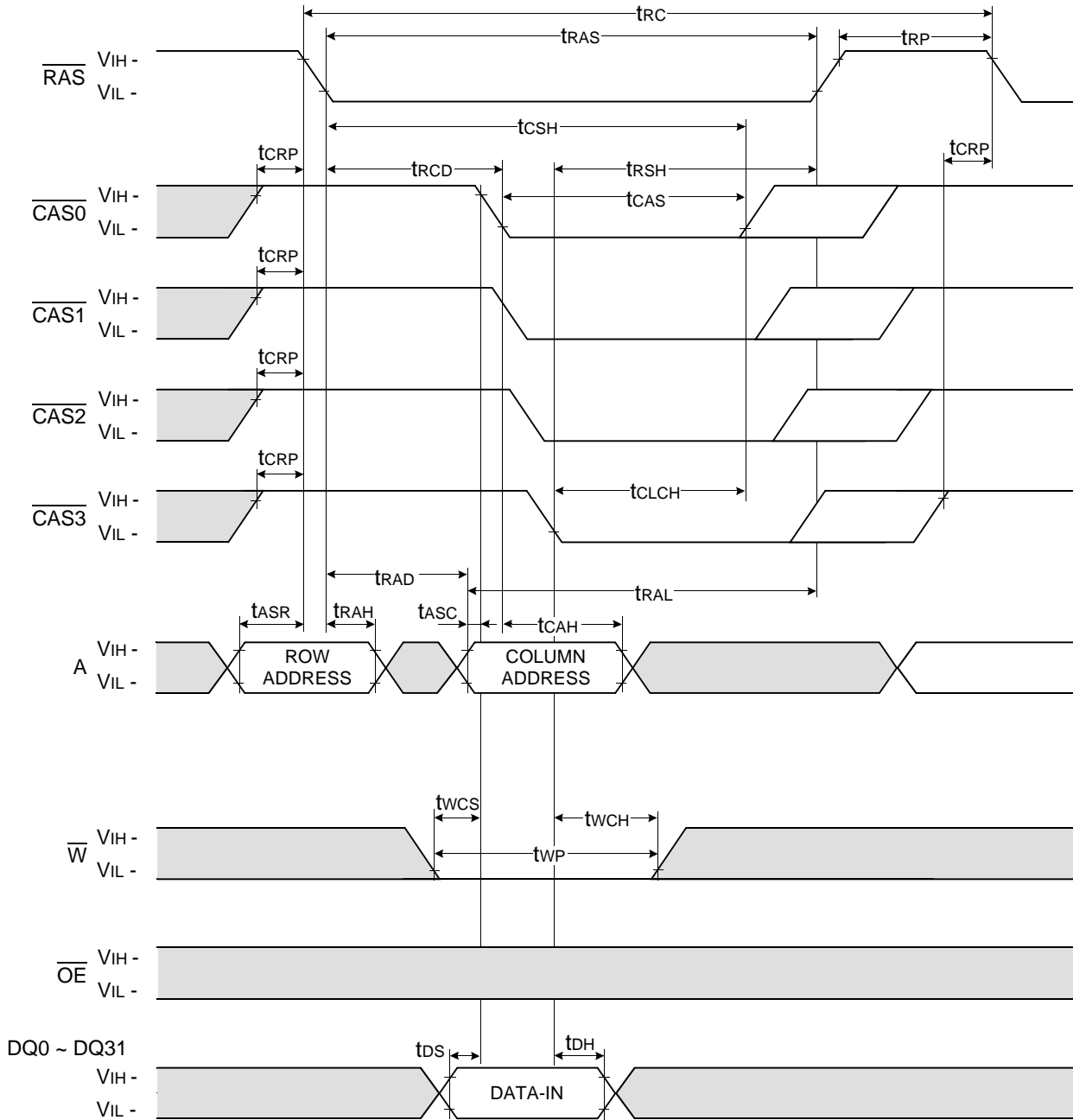
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2 WORDS WRITE CYCLE (EARLY WRITE)

NOTE : DOUT = OPEN



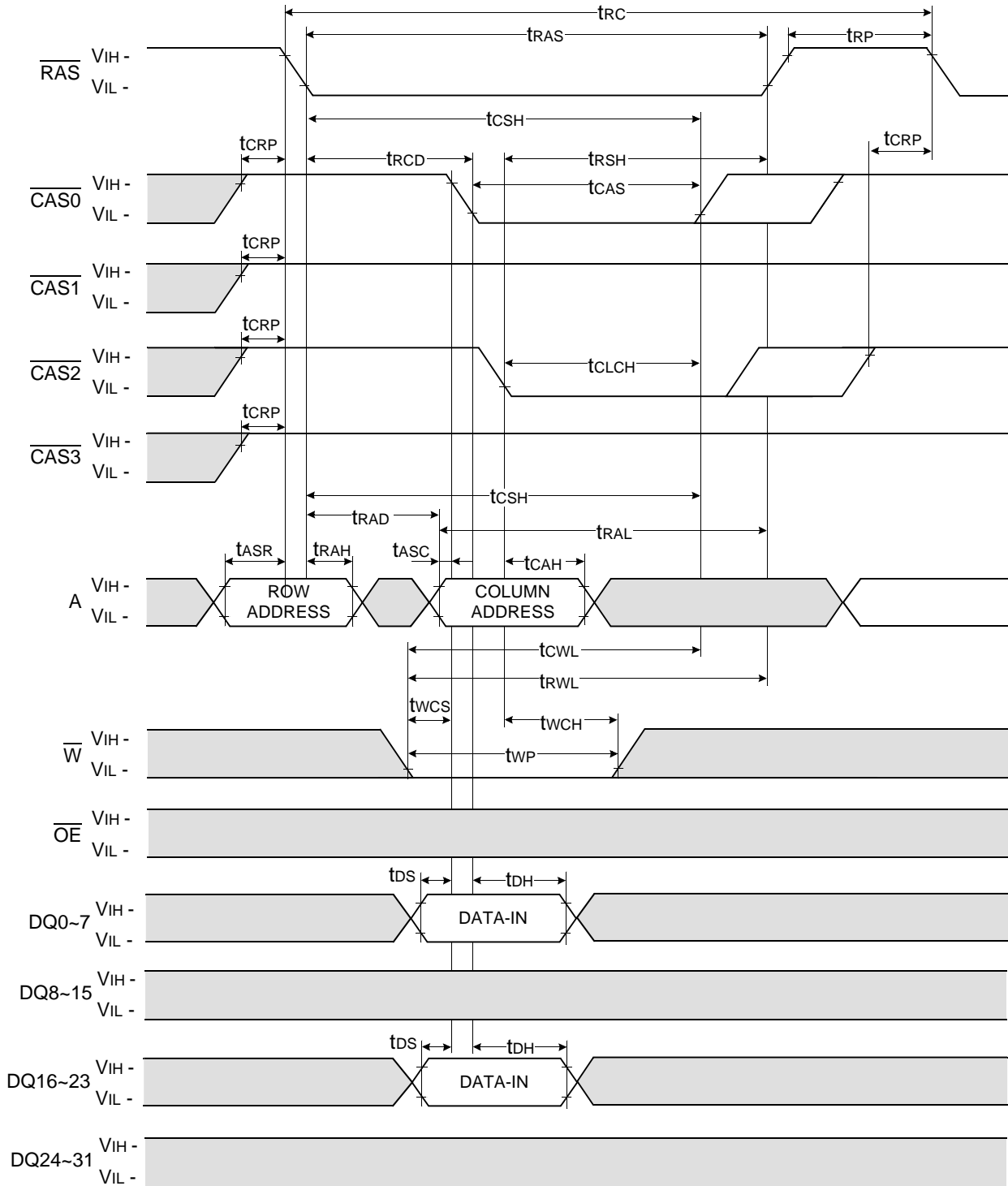
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 Undefined

K4Q153211M, K4Q153212M

CMOS DRAM

BYTE WIDE WRITE CYCLE (EARLY WRITE)

NOTE : DOUT = OPEN



Don't care
 Undefined

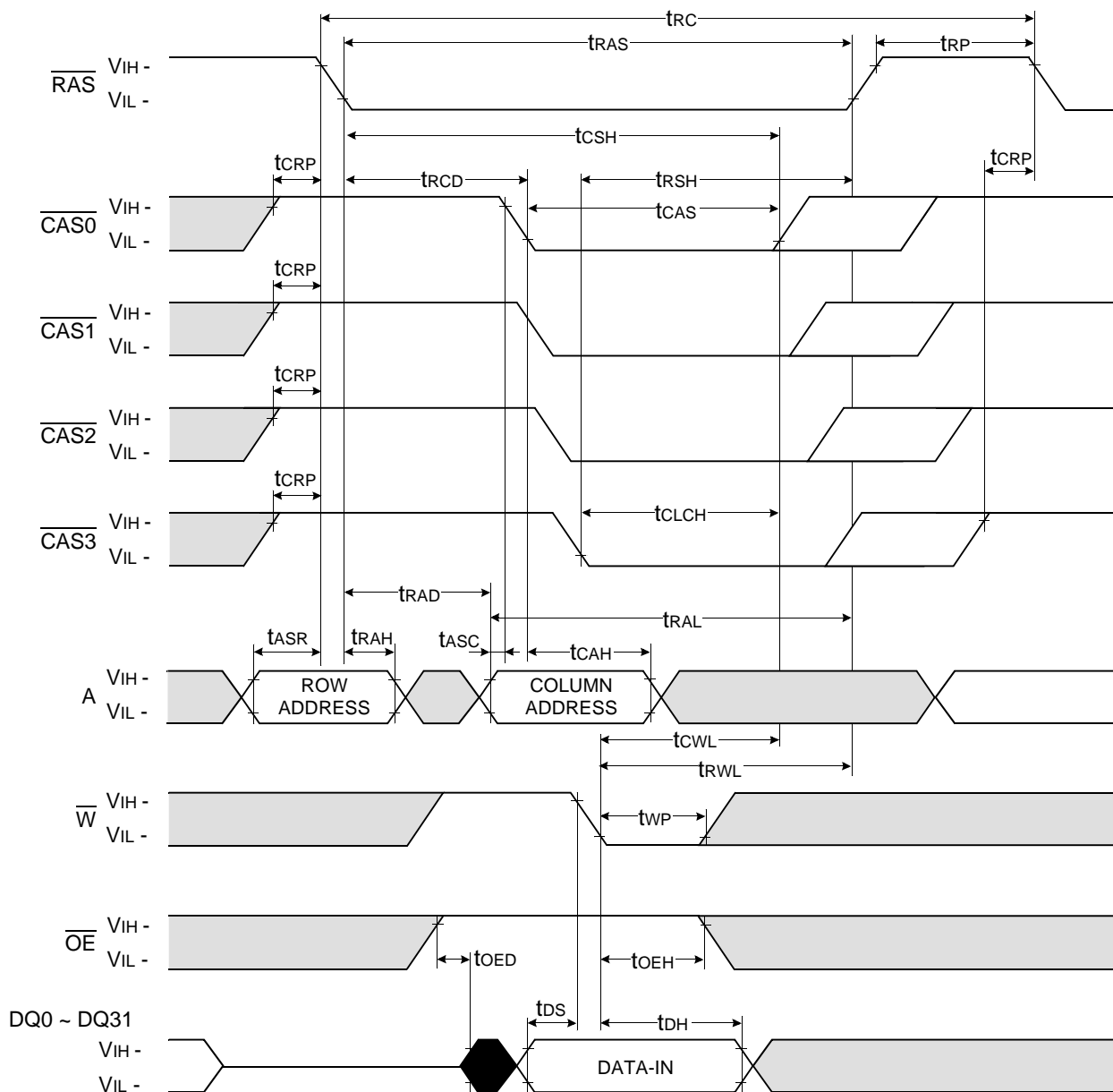


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CMOS DRAM

2 WORDS WRITE CYCLE (\overline{OE} CONTROLLED WRITE)

NOTE : DOUT = OPEN

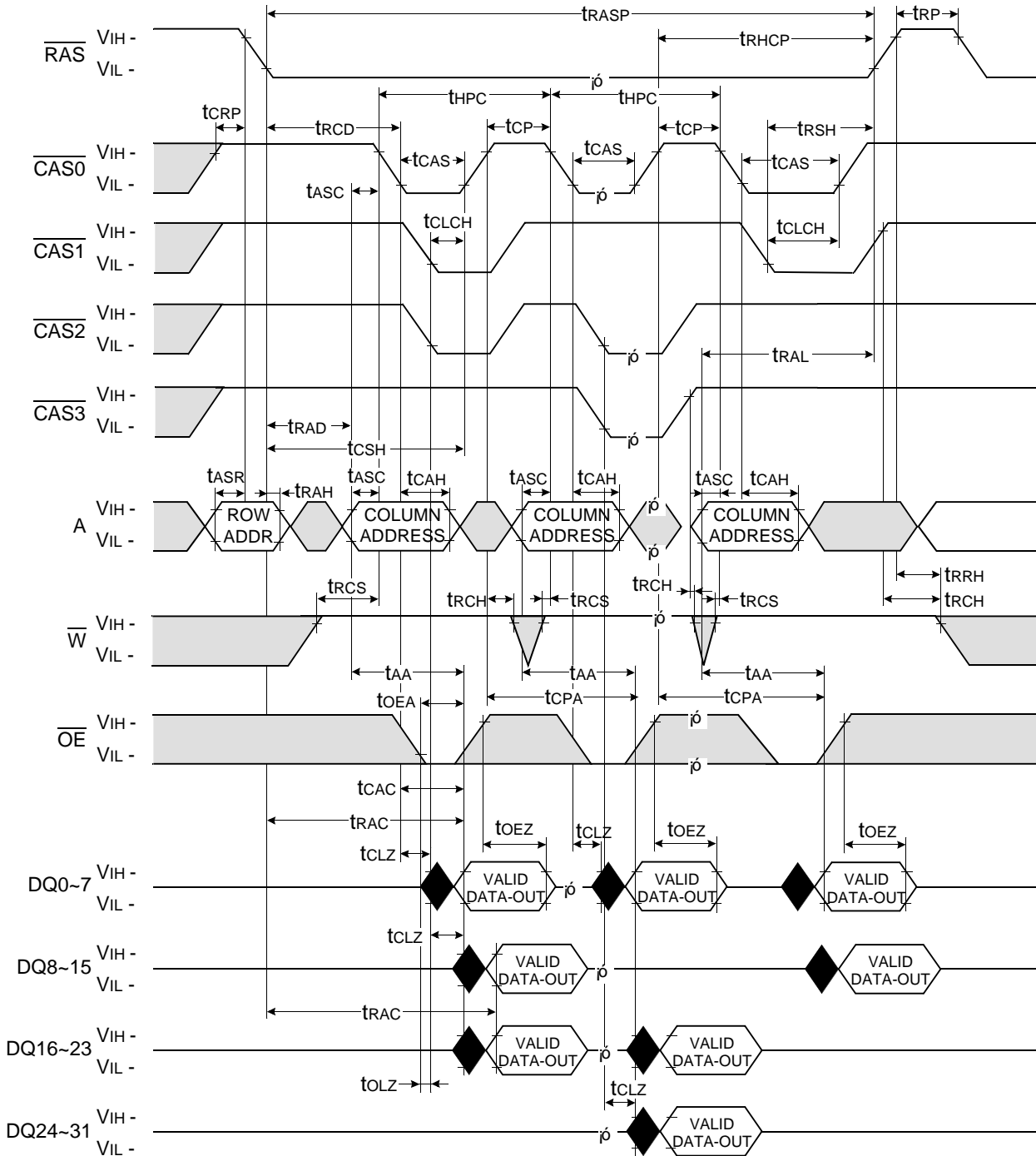


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CMOS DRAM

HYPER PAGE MODE READ CYCLE



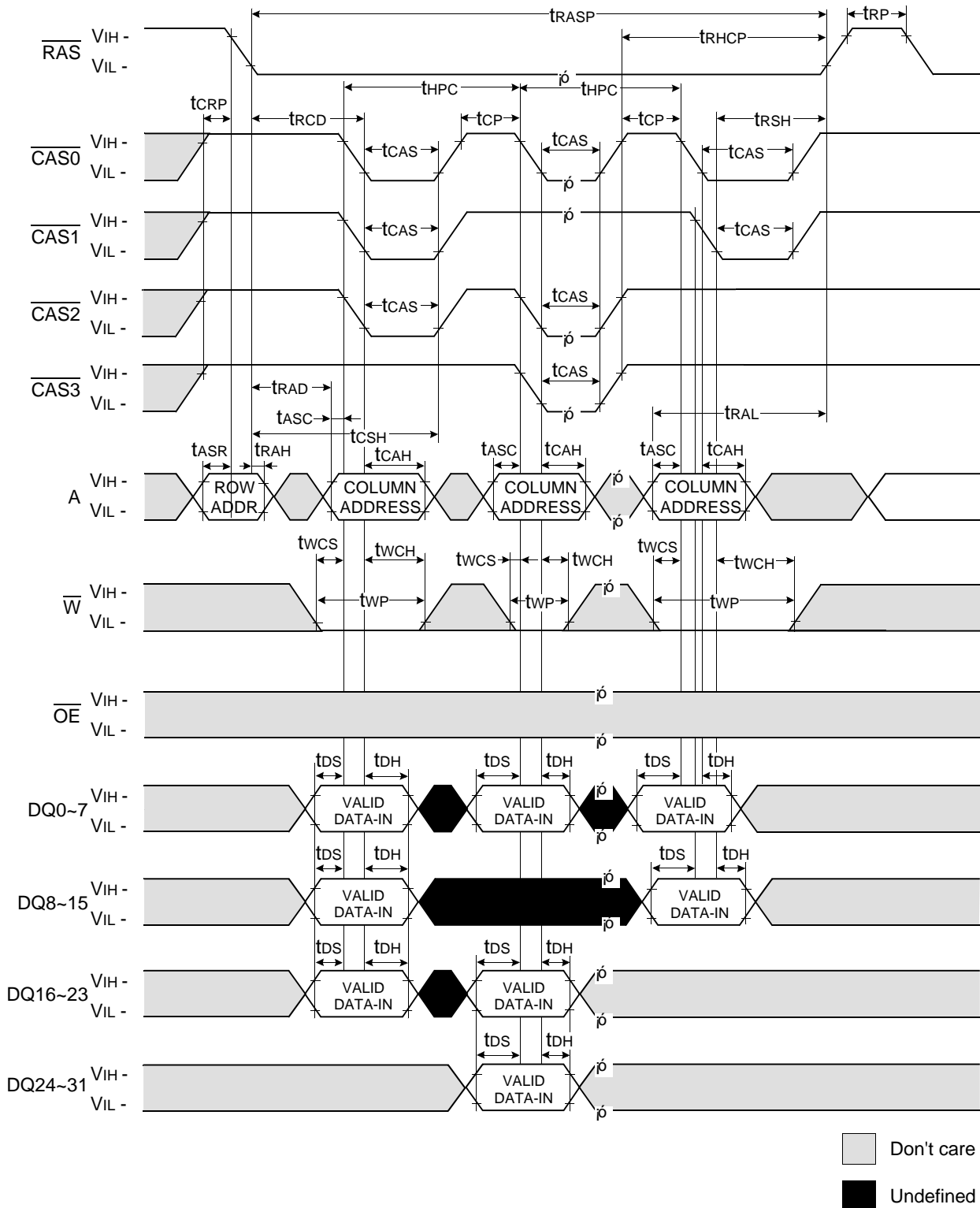
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CMOS DRAM

HYPER PAGE MODE WRITE CYCLE (EARLY WRITE)

NOTE : DOUT = OPEN



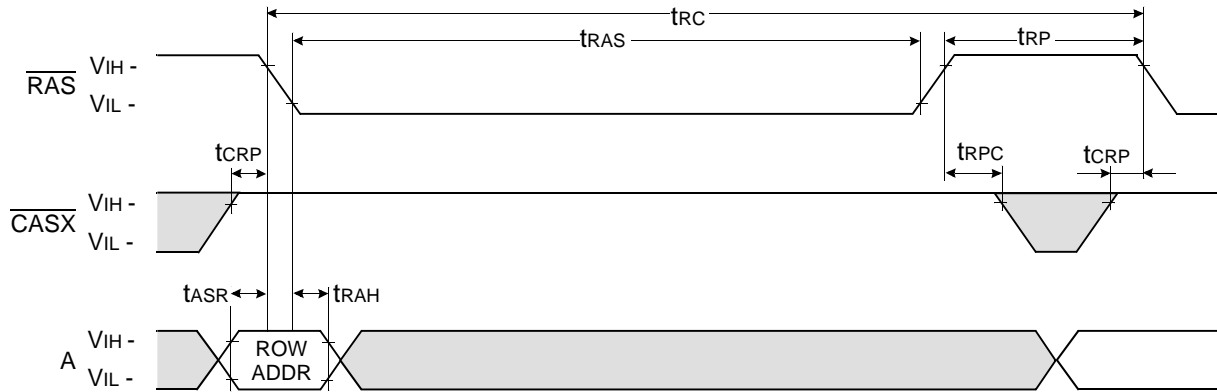
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CMOS DRAM

$\overline{\text{RAS}}$ - ONLY REFRESH CYCLE

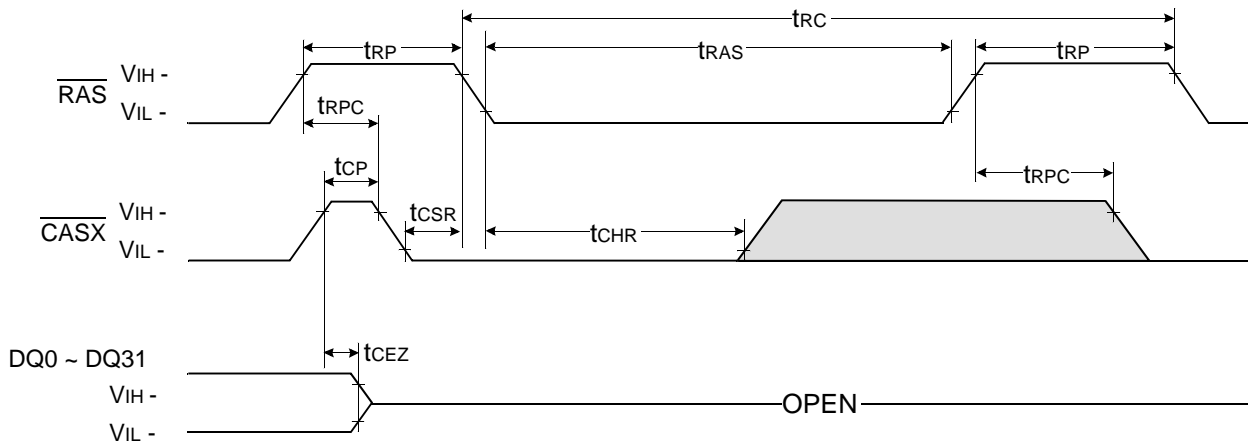
NOTE : $\overline{\text{W}}$, $\overline{\text{OE}}$, DIN = Don't care

DOUT = OPEN



$\overline{\text{CAS}}$ - BEFORE - $\overline{\text{RAS}}$ REFRESH CYCLE

NOTE : $\overline{\text{W}}$, $\overline{\text{OE}}$, A = Don't care



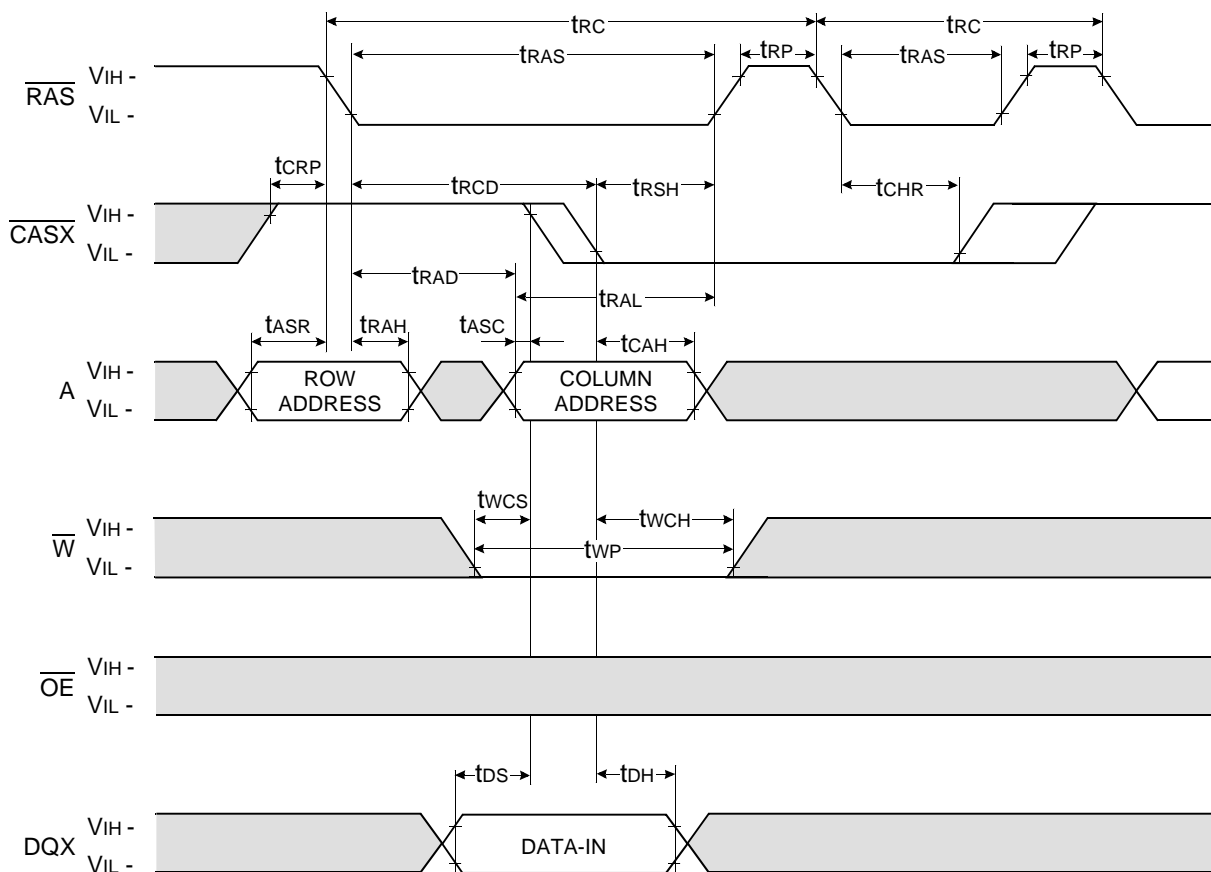
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HIDDEN REFRESH CYCLE (WRITE)

NOTE : DOUT = OPEN



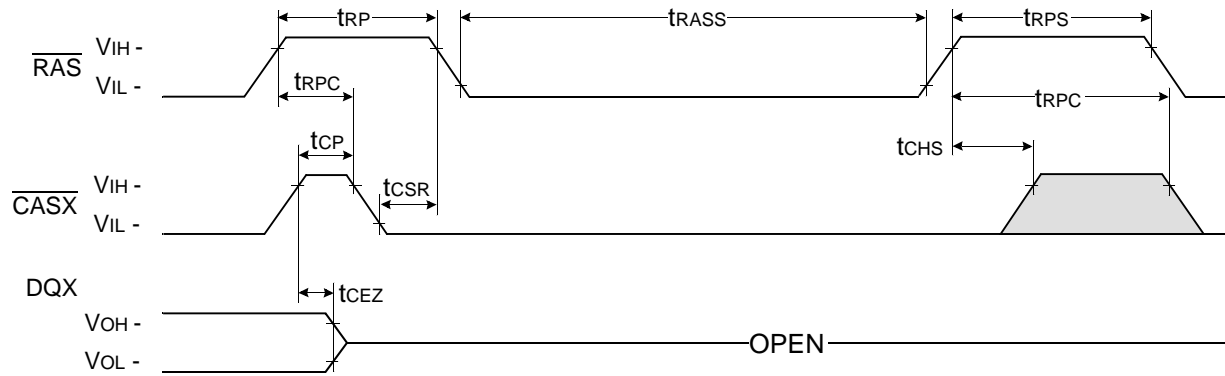
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$\overline{\text{CAS}}$ - BEFORE - $\overline{\text{RAS}}$ SELF REFRESH CYCLE

NOTE : $\overline{\text{OE}}$, A = Don't care



Don't care
 Undefined

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PACKAGE DIMENSIONS

Units : Inches (millimeters)

